

SPECIFICATION FOR LCD MODULE

MODULE NO: FUP 70723/REV

Doc. Version: 03Customer Approval:

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Accept	☐ Reject

APPROVAL FOR SPECIFICATIONS ONLY

■ APPROVAL FOR SPECIFICATIONS AND SAMPLE



1. Revision History

Sample Version	DOC. Version	DATE		DESCRIPTION	CHANGED BY
A0	00	2014-11-05	Spec Only	First issue	CJ /AC
A0	01	2014-12-19	Spec Only	Update 4.General Specification P.4 10.Black Light P.14	CJ/Y
A0	02	2014-12-23	Spec Only	Update 4.General Specification P.4 5. LCM drawing P.5 6. Electrical Characteristics P.6~P.9	CJ /Y
A0	03	2015-01-21	Full Spec	First sample	O /Y
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3. Module Numbering System:

Module Name: DSN50501-PCT

Part code: 800480S04AC

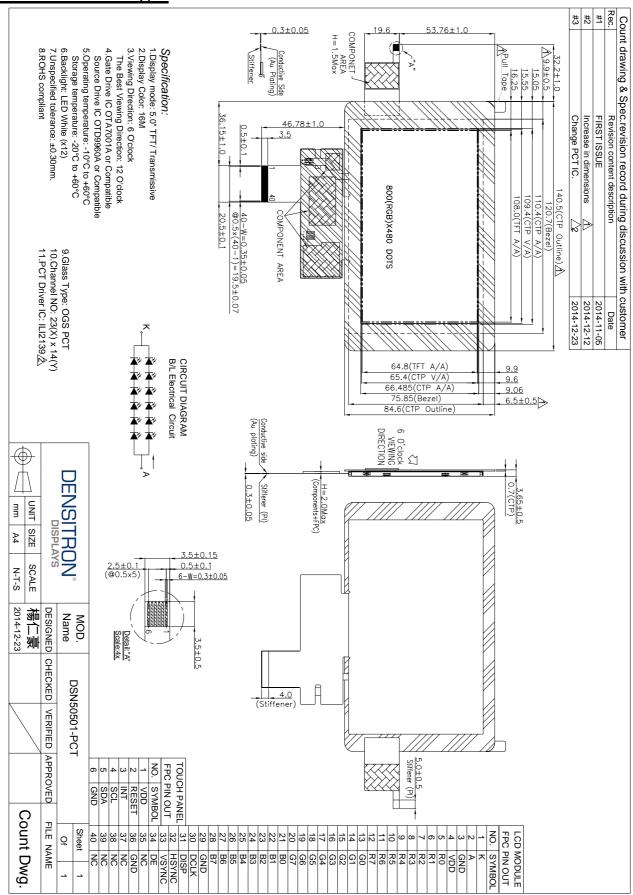


4. General Specification:

ITEM	CONTENTS				
Module Size	140.5(W) * 84.6(H) * 3.65(T) mm				
Module Size(With FPC)	172.7(W) * 131.38(H) *3.65(T) mm				
Display Size	5.0 inch				
Display Format	Graphic 800(RGB)* 480 Dot-matrix				
Active Area	108(W) *64.8(H) mm				
LCD Type	Active matrix TFT/ Transmissive				
Input Data	24 bit RGB interface				
Touch panel Type	REV™OGS+				
Viewing Direction (Gray inversion)	6 O'clock				
The Best Viewing Direction:	12 O'clock				
Gate Drive IC	OTA7001A or Compatible				
Source Drive IC	OTD9960A or Compatible				
RCT IC	ILI2139				
Weight	80.2g				



5. LCM drawing:





6. Electrical Characteristics:

6-1 Absolute Maximum Ratings

TFT IC OTA7001A+OTD9960A

Ta=25

Item	Symbol	Min.	Type	Max.	Unit	Remark
Power Voltage	VDD	-0.5	-	5.0	V	Note1 Note2
Operating Temperature	TOPR	-10	-	+60		Note1 Note2
Storage Temperature	TSTR	-20	-	+60		Note1 Note2

Note 1: The driver IC may be permanently damaged if it is used under the condition exceeding the above absolute maximum values. It is also recommended to use the driver IC within the limit of its electric characteristics during normal operation. Exceeding the conditions may lead to malfunction of it and affect its credibility.

Note 2: The voltage from GND.

Touch panel controller ILI2139

(Ta=25)

Item	Symbol	Min.	Туре	Max.	Unit	Remark
Power Supply voltage	VDD	-0.3	-	+3.6	Volt	-

6-2 Electrical Characteristics

TFT IC OTA7001A+OTD9960A

(Ta=25)

Item	Symbol		Rating	Unit	Remark		
Item	Symbol	Min	Тур	Max	Oilit	Kemark	
Power Voltage Logic	VDD	3.0	3.3	3.6	V	Note 1	
`Input voltage L level	VIL	GND	-	0.3*VDD	V	VDD=3.0	
Input voltage H level	VIH	0.7* VDD	-	VDD	V	V ~3.6V	
LCD Drive Power current	ILCD	-	60	90	mA	VDD= 3.3V	

Note1:

Vcom must be adjusted to optimize display quality: Cross-talk, Contrast Ratio and etc.

Touch panel controller ILI2139

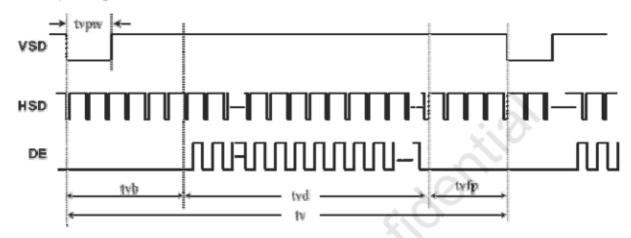
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply	$V_{ m DD}$	-	2.6	3.3	3.6	V



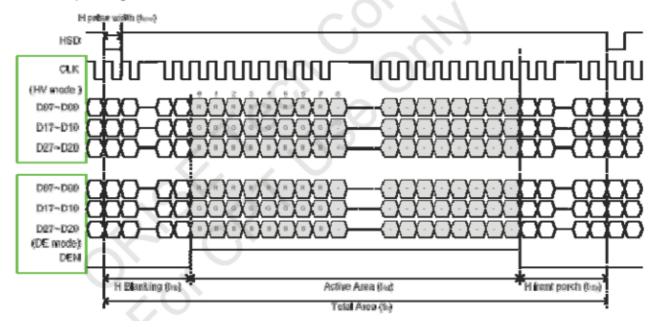
6-3 Timing Characteristics

6-3-1 TFT IC OTA7001A+OTD9960A Data Input Format

Vertical input timing



Horizontal input timing





6-3-2 TFT IC OTA7001A+OTD9960A Timing Conditions

Horizontal input timing

Parameter		Cumb al		Value			
		Symbol	Min.	Тур.	Max.	Unit	
Horizontal display ar	ea	thd		800		DCLK	
DCLK frequency		fclk	- 30 50			MHz	
1 Horizontal Line		th	928				
	Min.		1 npw 48				
HSD pulse width	Тур.	thpw				DCLK	
	Max.			_			
HSD Back Porch (Blanking)		thb	_	88	-		
HSD Front Porch	thfp	-	40	-			

Vertical input timing

Parameter	Symbol	Min.	Тур.	Max.	Unit
Vertical display area	tvd		480		H
VSD period time	tv		525	•	Н
VSD pulse width	tvpw	•	3	•	H
VSD Back Porch (Blanking)	t√b		32	5	Н
VSD Front Porch	t√fp	-	13		Н

8



6-3-3 Touch panel controller ILI2139 I2C Interface

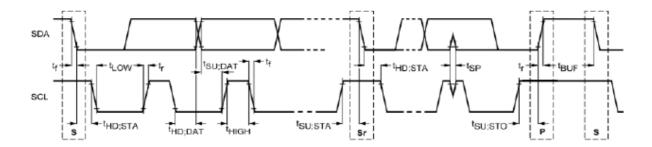


Figure 5-1: The timing of I²C Interface

Table 5-4: Characteristics of the SDA and SCL bus lines

Combal	Dawaratan		100KHz		400KHz			
Symbol	Parameter	Min	Max	Unit	Min	Max	Unit	
f _{SCL}	SCL clock frequency	0	100	kHz	0	400	kHz	
t _{HD;STA}	Hold time (repeated) START condition.	4.0	_	μs	0.6	_	μs	
	After this period, the first clock pulse is							
	generated							
t _{LOW}	LOW period of the SCL clock	4.7	_	μs	1.3	_	μs	
t _{HIGH}	HIGH period of the SCL clock	4.0	_	μs	0.6	-	μs	
t _{SU;STA}	Set-up time for a repeated START	4.7	_	μs	0.6	-	μs	
	condition							
t _{HD;DAT}	Data hold time	5.0	_	μs	-	-	μs	
	For I ² C Device	0	3.45	μs	0	0.9	μs	
t _{SU;DAT}	Data set-up time	250	-	ns	100	-	ns	
t _r	Rise time of both SDA and SCL signals	-	1000	ns	-	300	ns	
t _f	Fall time of both SDA and SCL signals	_	300	ns	_	300	ns	
t _{SU;STO}	Set-up time for STOP condition	4.0	_	μs	0.6	_	μs	
t _{BUF}	Bus free time between a STOP and	4.7	_	μs	1.3	_	μs	
	START condition							



7. Optical Characteristics:

Itom	Item		Conditio	Specificati		ons	Unit	Note
Item		Symbol	ns	Min	Тур	Max	Omt	NOTE
Transmitt	tance	T(%)	-	3.3	3.97	-	%	-
Contrast Ratio		CR	Θ=0 Normal Viewing angle	-	350	-		(1) (2)
Response	time	TR+TF	-	-	20	-	ms	(1) (3)
	Hor.	Өх+		ı	65	-		
Viewing	1101.	Өх-	C R 10	ı	65	-	deg.	(1)
angle	Ver.	⊖y+		-	50	-		(1)
	v G1.	Өу-		-	60	-		

Measuring Condition
1. Measuring surrounding: dark room
2. Ambient temperature: 25±2°C

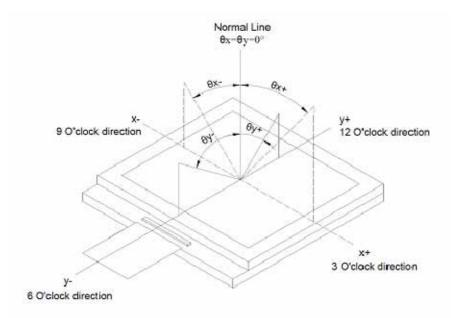
3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Тур.	Max.	Brightness
	Dad	X		0.5609	0.6109	0.6609	55.0 cd/m ²
	Red	y		0.3078	0.3578	0.4078	33.0 cu /III ²
Chromaticity	C	X	0 - 1 - 00	0.3004	0.3504	0.4004	200.0 cd/m ²
Coordinates	Green	y	$\theta = \phi = 0^{\circ}$ LED Backlight	0.5456	0.5956	0.6456	200.0 cu /III
(Transmissive)	Dlus	X		0.1052	0.1552	0.2052	50.0 cd/m ²
	Blue	у		0.0500	0.1000	0.1500	
	XX71-:4-	X		0.2441	0.2941	0.3441	300.0 cd/m ²
	White	y		0.2650	0.3150	0.3650	500.0 cu /m-



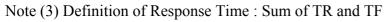
Note (1) Definition of Viewing Angle:

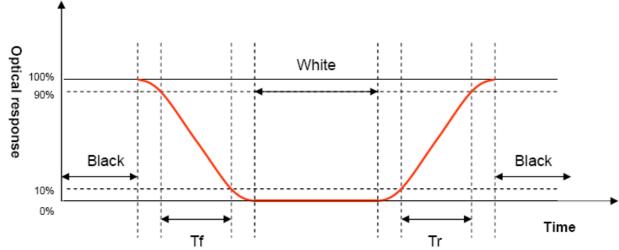


Note (2) Definition of Contrast Ratio(CR): measured at the center point of panel

Contrast ratio (CR)= Photo detector output when LCD is at "White" state

Photo detector output when LCD is at "Black







8. Interface Pin Assignment:

8-1 LCM FPC Interface

PIN NO.	Symbol	I/O	Description	
1	K	P	Power for LED backlight cathode	
2	A	P	Power for LED backlight anode	
3	GND	P	Power ground	
4	VDD	P	Power voltage	
5~12	R0~R7	I	Red data	
13~20	G0~G7	I	Green data	
21~28	B0~B7	I	Blue data	
29	GND	P	Power ground	
30	DCLK (CLK)	I	Pixel clock	
31	DISP	I	Display on/off	
32	HSYNC (HSD)	I	Horizontal sync signal	
33	VSYNC (VSD)	I	Vertical sync signal	
34	DEN (DE)	I	Data enable	
35	NC		No connect	
36	GND	P	Power ground	
37	NC(XR)		No connect (Touch Panel)	
38	NC(YD)		No connect (Touch Panel)	
39	NC(XL)		No connect (Touch Panel)	
40	NC(YU)		No connect (Touch Panel)	

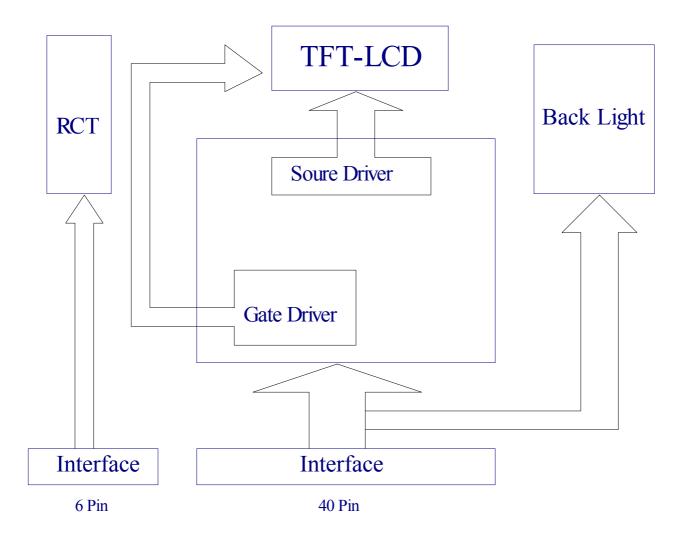


8-2 RCT Interface Pin

No.	Symbol Function	
1	VDD	Analog power supply.
2	RESET	RESET.
3	INT	External interrupt pin to host.
4	SCL	Serial clock pin for I2C interface.
5	SDA	Serial data pin for I2C interface.
6	GND	Ground.

Note: I2C interface

9. Back Diagram:





10. Backlight:

- 1. Standard Lamp Styles (Edge Lighting Type):
 The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.

3. Data About LED Backlight:

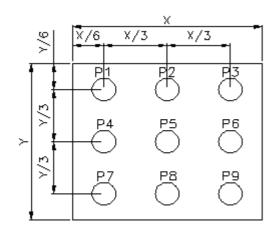
(Ta=25°C)

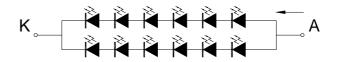
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	I		40		mA		
Voltage of the Backlight	V_{BL}	16.2	19.2	20.5	V	If=40mA	
Luminous Intensity for LCM	IV	250	300	-	cd/m ²	If=40mA	2
LED Life Time		20000	50000		Hr	If=40mA	4
Color		•		Wh	ite		

NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max * 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

Internal Circuit Diagram





(Effective spatial Distribution)

Hole Diameter ø10 mm; 1 to 9 per Position Measured Luminous



11. Standard Specification for Reliability .: 11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 60°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -10°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 60°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -20°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 40°C,75%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -10° C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +60°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static	Air: ± 6 KV 150pF/330 Ω 5 times
	Discharge	Contact: $\pm 4KV \ 150pF/330\Omega \ 5$ time

^{*}Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 12.2, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item Test Model		In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11-3. MTBF

Functions, performance, appearance, deterioration within 50,000 hours unconditions room temperature (25±5°C and in area not exposed to direct sun li	der ordinary operating and storage (2), normal humidity (50±10% RH),
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12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by F gpuktqp (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

- (i) Test method: According to MIL-STD105E.General Inspection Level

 take a single time.
- (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65% Minor defect: AQL = 2.5% Total defects: AQL = 2.5%

12-3. Non- conforming Analysis & Deal With Manners

- a. Non-conforming Analysis:
 - (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
 - (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
 - (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
- b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

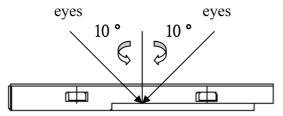
12-4. Agreement items

Both sides should discuss together when the following problems happen.

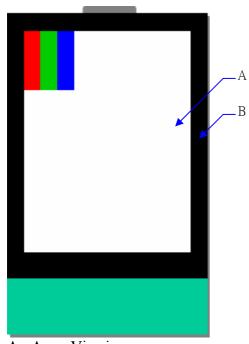
- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.



- 12-5. Standard of The Product Appearance Test
 - a. Manner of appearance test:
 - (i) The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at 30 ± 5 cm.
 - (ii) When test the model of transmissive product must add the reflective plate.
 - (iii)The test direction is base on around 10° of vertical line.
 - (iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area. (Outside viewing area)
- b. Basic principle:
 - (i) It will accord to the AQL when the standard can not be described.
 - (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
 - (iii) Must add new item on time when it is necessary.
 - c. Standard of inspection: (Unit: mm)



12-6. Inspection specification

Defect out of viewing area can be neglected.

NO	Item	Criterion A				AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 				0.65
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 Dot dimension as b $\Phi = (X+Y)/2$ $X \leftarrow \frac{1}{X}$ Y * Dens		Size(mm) $Φ \le 0.20$ $0.20 < Φ \le 0.40$ $0.40 < Φ$	Acceptable Q'ty Accept no dense 5 0	2.5
	LCD and Touch Panel	3.1 Round type: As follows: $\Phi = (X+Y)/2$ $X \leftarrow Y$ Y Y * Dens		Size(mm) $Φ \le 0.20$ $0.20 < Φ \le 0.40$ $0.40 < Φ$	Acceptable Q'ty Accept no dense 5 0	2.5
03	black spots, white spots, contamination (non – display)	* Densely spaced: No more than two			Acceptable Q'ty Accept no dense 4 Rejection Rejection lines within 3mm.	2.5



NO	Item	Criterion A				
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size Φ(mm) $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q'ty	Acceptable Q'ty Accept no dense 4 3 0 4	2.5	
05	Scratches	Follow NO.3 -2 Line Type.				
06	Chipped glass	L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface an $z = 1.1$ Chip on panel surface an $z = 1.1$ Chip thickness $z = 1.1$ Not over $z = 1$	s thickness a: LCD side and crack between panels width x : Chipper viewing area x is the total length of x width x is the total length of x width x is the total length of x area x and x area x and x area x and x area x area x area x area x and x area x area x area x and x area x area x and x area x area x and x area x area x area x and x area x area x and x area x and x area x area x and x area x area x and x area x and x area x area x and x area x and x area x and x area x area x and x area x and x area x and x area x area x and x area x and x area x and x area x and x area x area x and x area x and x area x area x and x are x	length 1/8a 1/8a each chip length 1/8a 1/8a 1/8a	2.5	



NO	Item	Criterion				
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:				
		y: Chip width x: Chip length z: Chip thickness				
		$y \le 0.5 \text{mm}$ $x \le 1/8 \text{a}$ $0 < z \le t$ $7.2.2$				
		Non-conductive portion:				
07	Glass crack	y Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z	2.5			
		y: Chip width x: Chip length z: Chip thickness				
		$y \le L \qquad x \le 1/8a \qquad 0 < z \le t$				
		 ⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack y: width x: length y ≤ 1/3L X ≤ a				



NO	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	РСВ, СОВ	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function, we judge accept.	2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65



NO	Item	Criterion A				
		Symbols: x: Chip length k: Seal width length L: Electrode pad length 14.1 General glass claused 14.1.1 Chip on panel	t: Touch Panel Total t			
			y k			
		z: Chip thickness	y: Chip width	x: Chip length		
14	Touch Panel Chipped	Z≦t	$\leq 1/2$ k and not over viewing area	x≤1/8a	2.5	
	glass	 ⊙ Unit: mm ⊙ If there are 2 or m 14.1.2 Corner crack: 	nore chips, x is the total	length of each chip		
		z: Chip thickness	y: Chip width	x: Chip length		
		z≦t	≤1/2 k and not over viewing area	x ≤ 1/8a		
		⊙ Unit: mm⊙ If there are 2 or m	nore chips, x is the total	length of each chip		



NO	Item	Criterion	
15	Touch Panel(Fish eye)		2.5
		L>0.7mm 0	
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	
17	Touch Panel Linearity	Less than 2.5% is acceptable.	
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	
20	Definition of Pixel	Pixel: Group of Three Sub-pixels (Red, Green, Blue): Dot: Red or Green or Blue Or Or Dot: Any sub-pixel Bright Dot Defects Dots (sub-pixels) on display which is bright in the picture and visible at Black Pattern. Dark Dot Defects Dots(sub-pixels) on display which is dark in the picture and visible at Red/Green/Black/White Pattern. Neighbour Dot Defects Two or three neighbour dots (dot: sub-pixel) cluster(R&G,G&B,B&R,or	



	T4	Torono ettero Outkoute		
NOTE: Dot out of VA can be ignored.				
	R&G&B).Dot Defects Inspection Criteria			

Items	Inspection Criteria		
	Details	Allowed quantity	
Bright Dot	Not Neighbour Dot	2	
Dark Dot	Not Neighbour Dot	3	
Total acce	5		

[•] Size of dot defect is larger than half of one sub-pixel.



13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10 , and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 280±10 and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Guarantee:

Our products meet requirements of the environment. Out ROHS requirement is based on European Union Directive 2011/65/EU (ROHS) Requirements and Update.